



SPN50T10 N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN50T10 is the N-Channel logic enhancement mode power field effect transistor which is produced using super high cell density DMOS trench technology. The SPN80T10 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

FEATURES

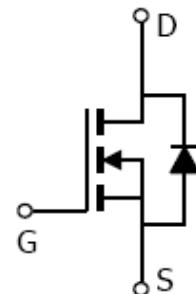
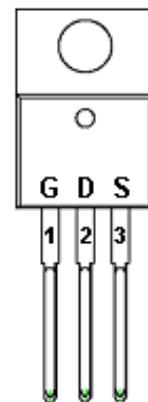
- ◆ 100V/65A, $R_{DS(ON)}=18m\Omega$ @ $V_{GS}= 10V$
- ◆ High density cell design for extremely low RDS (ON)
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TO-220 package design

APPLICATIONS

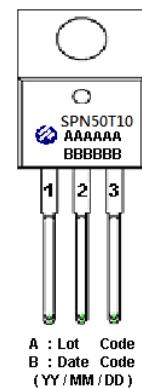
- Powered System
- DC/DC Converter
- Load Switch

PIN CONFIGURATION

TO-220



PART MARKING





SPN50T10

N-Channel Enhancement Mode MOSFET

PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN50T10T220TGB	TO-220-3L	SPN50T10

※ SPN50T10T220TGB : Tube ; Pb – Free ; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	VDSS	100	V
Gate –Source Voltage	VGSS	±20	V
Continuous Drain Current(TJ=150°C)	TA=25°C	65	A
	TA=70°C	40	
Pulsed Drain Current	IDM	200	A
Power Dissipation @ TA=25°C	PD	166	W
Operating Junction Temperature	TJ	-55/150	°C
Storage Temperature Range	TSTG	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	62	°C/W



SPN50T10

N-Channel Enhancement Mode MOSFET

ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V, ID=250uA	100			V
Gate Threshold Voltage	VGS(th)	VDS=VGS, ID=250uA	2.0		4.0	
Gate Leakage Current	IGSS	VDS=0V, VGS=±20V			±100	nA
Zero Gate Voltage Drain Current	IDSS	VDS=80V, VGS=0V			25	uA
		VDS=80V, VGS=0V TJ=125°C			100	
Drain-Source On-Resistance	RDS(on)	VGS= 10V, ID=30A			18	mΩ
Forward Transconductance	gfs	VDS=10V, ID=30A		75		S
Diode Forward Voltage	VSD	IS=30A, VGS =0V			1.3	V
Dynamic						
Total Gate Charge	Qg	VDS=80V, VGS=10V ID= 40A		115	180	nC
Gate-Source Charge	Qgs			20		
Gate-Drain Charge	Qgd			48		
Input Capacitance	Ciss	VDS=25, VGS=0V f=1MHz		6000	9600	pF
Output Capacitance	Coss			550		
Reverse Transfer Capacitance	Crss			300		
Turn-On Time	td(on)	VDD=50V, RL=1Ω ID=30A, VGEN=10V RG=1.66Ω		21		nS
	tr			58		
Turn-Off Time	td(off)			41		
	tf			15		



SPN50T10 N-Channel Enhancement Mode MOSFET

TYPICAL CHARACTERISTICS

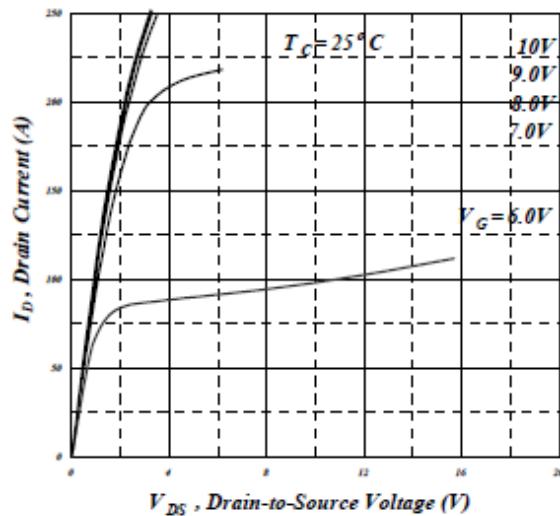


Fig 1. Typical Output Characteristics

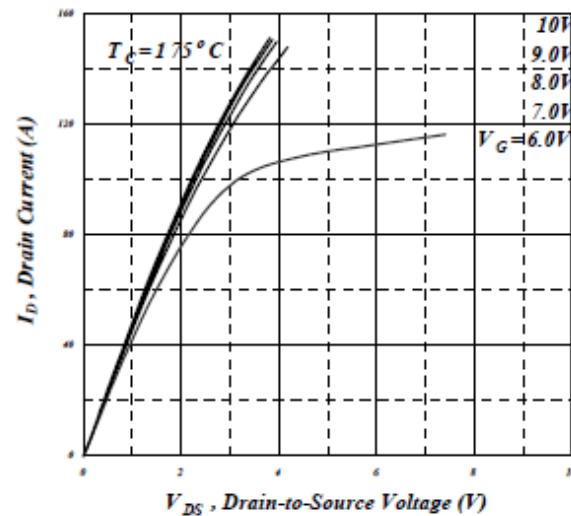


Fig 2. Typical Output Characteristics

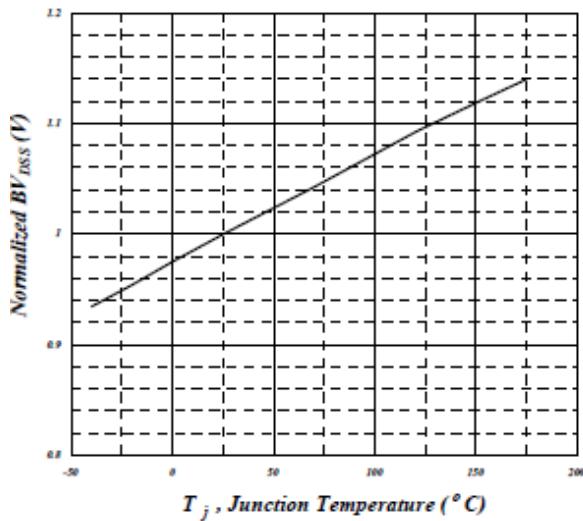


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

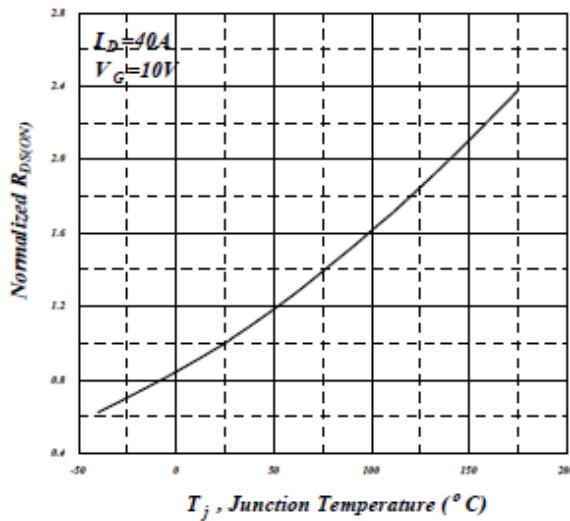


Fig 4. Normalized On-Resistance v.s. Junction Temperature



SPN50T10 N-Channel Enhancement Mode MOSFET

TYPICAL CHARACTERISTICS

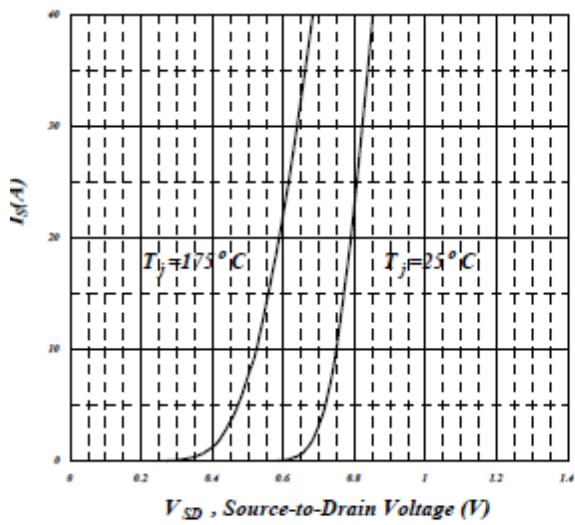


Fig 5. Forward Characteristic of Reverse Diode

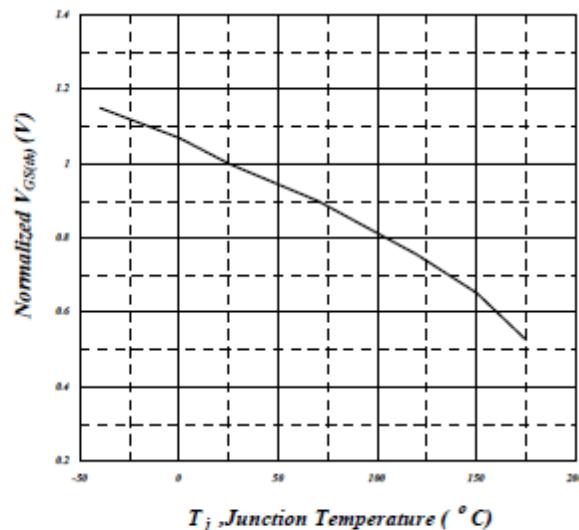


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

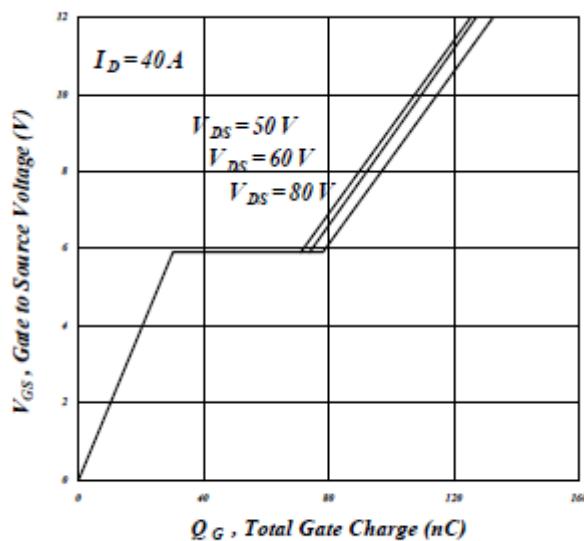


Fig 7. Gate Charge Characteristics

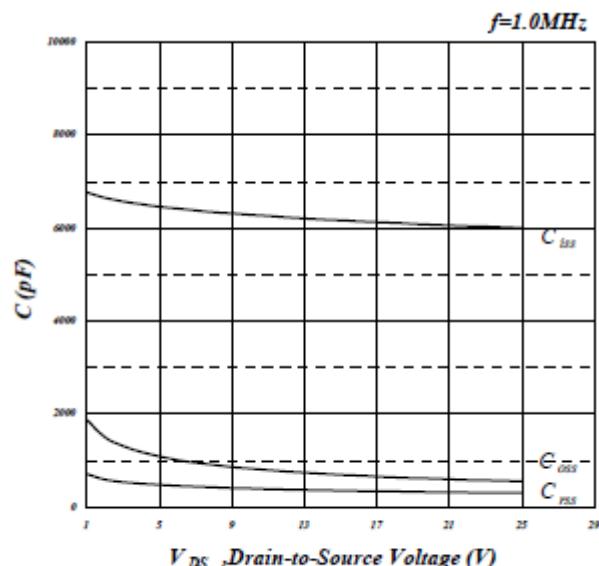


Fig 8. Typical Capacitance Characteristics



SPN50T10 N-Channel Enhancement Mode MOSFET

TYPICAL CHARACTERISTICS

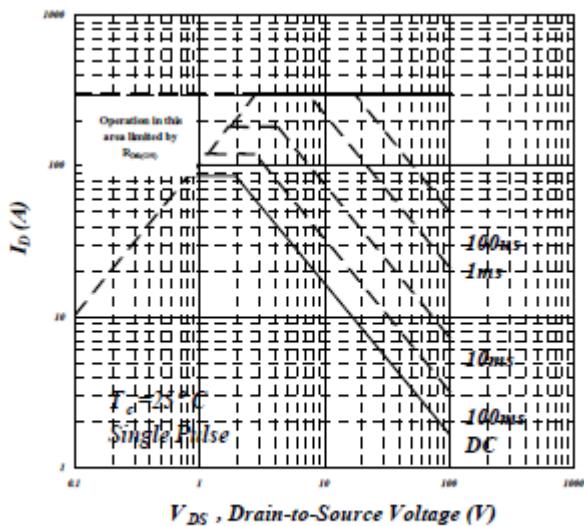


Fig 9. Maximum Safe Operating Area

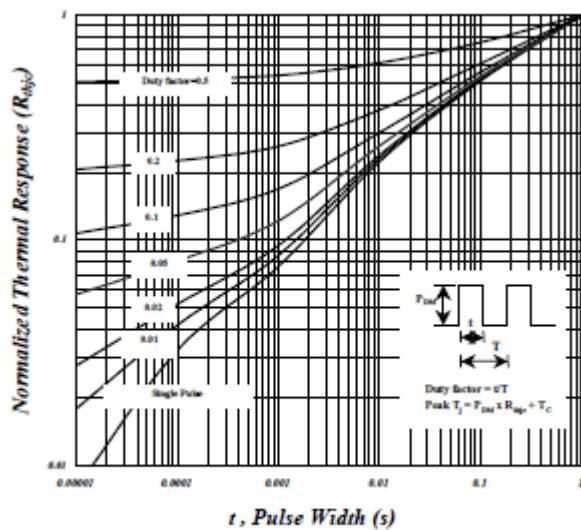


Fig 10. Effective Transient Thermal Impedance

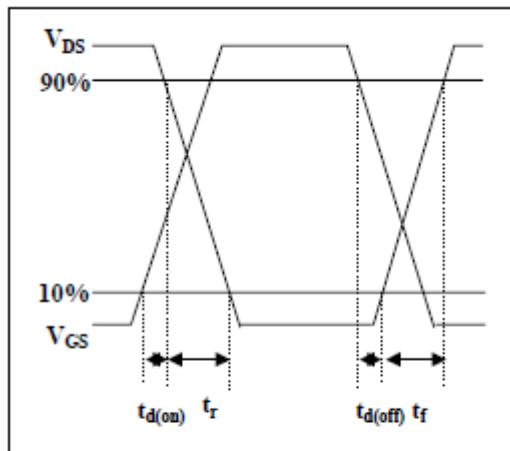


Fig 11. Switching Time Waveform

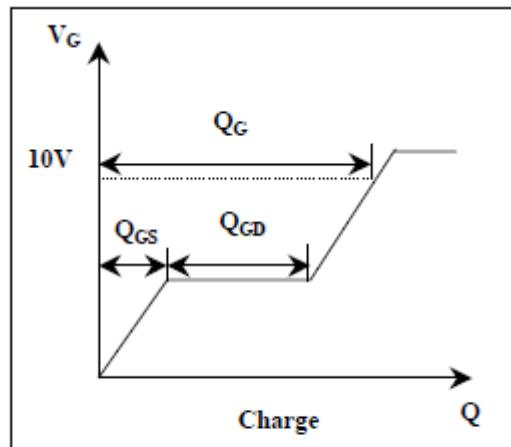


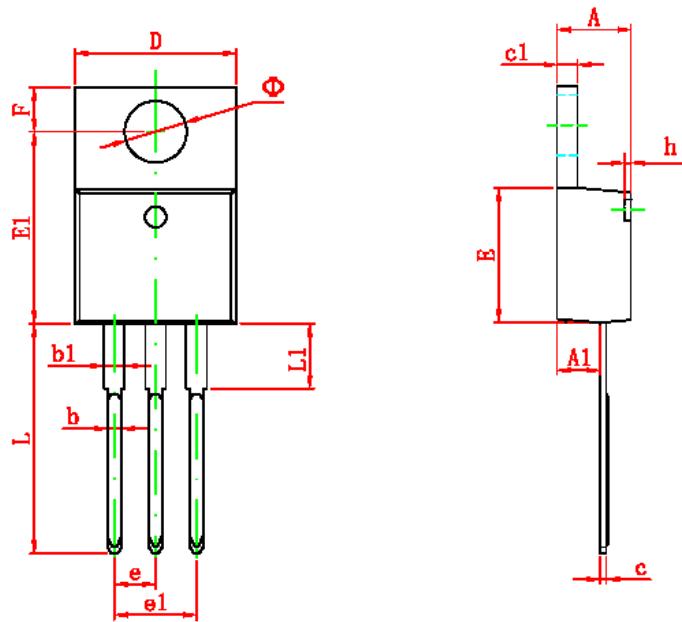
Fig 12. Gate Charge Waveform



SPN50T10

N-Channel Enhancement Mode MOSFET

TO-220 PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.470	4.670	0.176	0.184
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
E1	12.060	12.460	0.475	0.491
e	2.540 TYP		0.100 TYP	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
h	0.000	0.300	0.000	0.012
L	13.400	13.800	0.528	0.543
L1	3.560	3.960	0.140	0.156
• •	3.735	3.935	0.147	0.155



SPN50T10

N-Channel Enhancement Mode MOSFET

Information provided is alleged to be exact and consistent. SYNC Power Corporation presumes no responsibility for the penalties of use of such information or for any violation of patents or other rights of third parties which may result from its use. No license is granted by allegation or otherwise under any patent or patent rights of SYNC Power Corporation. Conditions mentioned in this publication are subject to change without notice. This publication surpasses and replaces all information previously supplied. SYNC Power Corporation products are not authorized for use as critical components in life support devices or systems without express written approval of SYNC Power Corporation.

©The SYNC Power logo is a registered trademark of SYNC Power Corporation

©2004 SYNC Power Corporation – Printed in Taiwan – All Rights Reserved

SYNC Power Corporation

7F-2, No.3-1, Park Street

NanKang District (NKSP), Taipei, Taiwan 115

Phone: 886-2-2655-8178

Fax: 886-2-2655-8468

©<http://www.syncpower.com>